

Data Sheet

### April 2003

## Low-Voltage, Single Supply, 4 to 1 Multiplexer, High Performance Analog Switch

intersil

The Intersil ISL43640 is a precision, bidirectional, analog switch configured as a 4 channel multiplexer / demultiplexer. The ISL43640 is designed to operate from a single +2V to +12V supply. It is equiped with an inhibit pin to simultaneously open all signal paths.

ON resistance is  $115\Omega$  with a +5V supply,  $45\Omega$  with a +12V supply, and  $190\Omega$  with a +3V supply. Each switch can handle rail to rail analog signals. The off-leakage current is only 1nA at  $25^{\circ}$ C or 2.5nA at  $85^{\circ}$ C. All digital inputs have 0.8V to 2.4V logic thresholds ensuring TTL/CMOS logic compatibility when using a single +5V supply. Some of the smallest packages are available, alleviating board space limitations, and making Intersil's newest line of low-voltage switches an ideal solution.

Table 1 summarizes the performance of this switch.

### TABLE 1. FEATURES AT A GLANCE

CONFIGURATION	4:1 MUX
12V R <sub>ON</sub>	45Ω
12V t <sub>ON</sub> /t <sub>OFF</sub>	25ns/24ns
4.5V R <sub>ON</sub>	115Ω
4.5V t <sub>ON</sub> /t <sub>OFF</sub>	60ns/30ns
3V R <sub>ON</sub>	190Ω
3V t <sub>ON</sub> /t <sub>OFF</sub>	120ns/45ns
Packages	10 Ld MSOP, 16 Ld QFN 3x3

## **Related Literature**

- Technical Brief TB363 "Guidelines for Handling and Processing Moisture Sensitive Surface Mount Devices (SMDs)"
- Application Note AN557 "Recommended Test Procedures for Analog Switches"

### Features

- Fully Specified at 3V, 5V, and 12V Supplies for 10% Tolerances
- ON Resistance ( $R_{ON}$ ) Max,  $V_S = 5V \dots 120\Omega$
- R<sub>ON</sub> Matching Between Channels.....<2Ω</li>
- Single Supply Operation.....+2V to +12V

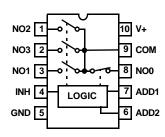
- Guaranteed Break-Before-Make
- TTL, CMOS Compatible
- Available in 10 Ld MSOP and 16 Ld QFN Packages

## Applications

- · Battery Powered, Handheld, and Portable Equipment
- Communications Systems
  - Radios
  - Telecom Infrastructure
  - ADSL, VDSL Modems
- Test Equipment
  - Medical Ultrasound
  - Electrocardiograph
  - Magnetic Resonance Image
  - CT and PET Scanners (MRI)
  - ATE
- Audio and Video Switching
- Various Circuits
  - +3V/+5V DACs and ADCs
  - Sample and Hold Circuits
  - Operational Amplifier Gain Switching Networks
  - High Frequency Analog Switching
  - High Speed Multiplexing
  - Integrator Reset Circuits

Pinouts (Note 1)

ISL43640 (MSOP) TOP VIEW



NOTE:

1. Switches Shown for Logic "0" Inputs.

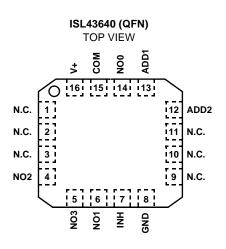
## Truth Table

ISL43640							
INH	ADD2 ADD1 SWITCH OF						
1	Х	Х	NONE				
0	0	0	NO0				
0	0	1	NO1				
0	1	0	NO2				
0	1	1	NO3				

NOTE: Logic "0"  ${\leq}0.8V.$  Logic "1"  ${\geq}2.4V,$  with  $V_S$  between 3.3V and 11V.

## **Pin Descriptions**

PIN	FUNCTION
V+	System Power Supply Input (+2V to +12V)
GND	Ground Connection
INH	Digital Control Input. Connect to GND for Normal Operation. Connect to V+ to turn all switches off.
COM	Analog Switch Common Pin
NO	Analog Switch Normally Open Pin
ADD	Address Input Pin
N.C.	No Internal Connection



## **Ordering Information**

PART NO. (BRAND)	TEMP. RANGE ( <sup>o</sup> C)	PACKAGE	PKG. NO.
ISL43640IU (640I)	-40 to 85	10 Ld MSOP	M10.118
ISL43640IU-T (640I)	-40 to 85	10 Ld MSOP Tape and Reel	M10.118
ISL43640IR * (640I)	-40 to 85	16 Ld QFN	L16.3X3
ISL43640IR-T * (640I)	-40 to 85	16 Ld QFN Tape and Reel	L16.3X3

\* In Development.

### **Absolute Maximum Ratings**

### **Operating Conditions**

**Temperature Range** ISL43640IX ..... .....-40°C to 85°C

### **Thermal Information**

Thermal Resistance (Typical)	θ <sub>JA</sub> ( <sup>o</sup> C/W)
10 Ld MSOP Package (Note 3)	. 190
16 Ld QFN Package (Note 4)	. 62
Maximum Junction Temperature (Plastic Package) .	150 <sup>0</sup> C
Moisture Sensitivity (See Technical Brief TB363)	
MSOP Package	Level 1
QFN Package	Level 2
Maximum Storage Temperature Range	-65 <sup>0</sup> C to 150 <sup>0</sup> C
Maximum Lead Temperature (Soldering 10s) (MSOP - Lead Tips Only)	300 <sup>0</sup> C

MAX

V+

118

150

3

5

13

18

1

2.5

1

2.5

1

5

-

UNITS

V

Ω

Ω

Ω

Ω

Ω

Ω

nA

nA

nA

nA

nA

nA

V

CAUTION: Stresses above those listed in "Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress only rating and operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied.

#### NOTES:

- 2. Signals on NC, NO, COM, ADD, or INH exceeding V+ or GND are clamped by internal diodes. Limit forward diode current to maximum current ratings.
- 3.  $\theta_{JA}$  is measured with the component mounted on a low effective thermal conductivity test board in free air. See Tech Brief TB379 for details.
- 4.  $\theta_{1\Delta}$  is measured in free air with the component mounted on a high effective thermal conductivity test board with "direct attach" features. See Tech Brief TB379.

#### Electrical Specifications +5V Supply Test Conditions: V = +4.5V to +5.5V, GND = 0V, $V_{INH} = 2.4V$ , $V_{INI} = 0.8V$ (Note 4), Unless Otherwise Specified TEMP (NOTE 5) (NOTE 5) PARAMETER **TEST CONDITIONS** (°C) MIN TYP ANALOG SWITCH CHARACTERISTICS Analog Signal Range, VANALOG Full 0 -ON Resistance, RON $V_{+} = 4.5V, I_{COM} = 1.0mA, V_{NO} \text{ or } V_{NC} = 3.5V,$ 25 115 -See Figure 5 Full --V+ = 4.5V, I<sub>COM</sub> = 1.0mA, V<sub>NO</sub> or V<sub>NC</sub> = 3.5V, Note 7 RON Matching Between Channels, 25 -1 ΔRON Full \_ -RON Flatness, RFLAT(ON) V+ = 5.5V, $I_{COM}$ = 1.0mA, $V_{NO}$ or $V_{NC}$ = 1.5V, 2.5V, 25 \_ 12 3.5V. Note 8 Full 13 -V+ = 5.5V, $V_{COM}$ = 1V, 4.5V, $V_{NO}$ or $V_{NC}$ = 4.5V, 1V, NO or NC OFF Leakage Current, 25 -1 -INO(OFF) or INC(OFF) Note 6 Full -2.5 -COM OFF Leakage Current, $V + = 5.5V, V_{COM} = 4.5V, 1V, V_{NO} \text{ or } V_{NC} = 1V, 4.5V,$ 25 -1 -Note 6 ICOM(OFF) Full -2.5 COM ON Leakage Current, V+ = 5.5V, $V_{COM}$ = 1V, 4.5V, or $V_{NO}$ or $V_{NC}$ = 1V, 25 -1 -4.5V, or Floating, Note 6 ICOM(ON) Full -5 -DIGITAL INPUT CHARACTERISTICS Input Voltage High, VINH Full 2.4 1.4

Input Voltage Low, VINL		Full	-	1.3	0.8	V
Input Current, I <sub>INH</sub> , I <sub>INL</sub>	V+ = 5.5V, V <sub>IN</sub> = 0V or V+	Full	-0.5	-	0.5	μA
DYNAMIC CHARACTERISTICS	·					
Inhibit Turn-ON Time, t <sub>ON</sub>	V+ = 4.5V, V <sub>NO</sub> or V <sub>NC</sub> = 3V, R <sub>L</sub> =300 $\Omega$ , C <sub>L</sub> = 35pF,	25	-	60	65	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	80	ns
Inhibit Turn-OFF Time, t <sub>OFF</sub>	V+ = 4.5V, V <sub>NO</sub> or V <sub>NC</sub> = 3V, R <sub>L</sub> =300 $\Omega$ , C <sub>L</sub> = 35pF,	25	-	30	35	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	40	ns
Address Transition Time, t <sub>TRANS</sub>	V+ = 4.5V, V <sub>NO</sub> or V <sub>NC</sub> = 3V, R <sub>L</sub> =300 $\Omega$ , C <sub>L</sub> = 35pF,	25	-	61	70	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	85	ns
Break-Before-Make Time Delay, t <sub>D</sub>	V+ = 5.5V, R <sub>L</sub> = 300 $\Omega$ , C <sub>L</sub> = 35pF, V <sub>NO</sub> = V <sub>NC</sub> = 3V, V <sub>IN</sub> = 0 to 3, See Figure 3	Full	5	16	-	ns

### Electrical Specifications +5V Supply

Y Test Conditions: V+ = +4.5V to +5.5V, GND = 0V, V<sub>INH</sub> = 2.4V, V<sub>INL</sub> = 0.8V (Note 4), Unless Otherwise Specified (Continued)

PARAMETER	TEST CONDITIONS	TEMP ( <sup>o</sup> C)	(NOTE 5) MIN	ТҮР	(NOTE 5) MAX	UNITS
Charge Injection, Q	$C_L = 1.0nF, V_G = 0V, R_G = 0\Omega$ , See Figure 2	25	-	0.3	1	рС
OFF Isolation	$R_L = 50\Omega$ , $C_L = 5pF$ , f = 1MHz, See Figure 4	25	-	75	-	dB
NO or NC OFF Capacitance, COFF	$f = 1MHz$ , $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	4	-	pF
COM OFF Capacitance, C <sub>COM(OFF)</sub>	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	11	-	pF
COM ON Capacitance, C <sub>COM(ON)</sub>	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	20	-	pF
POWER SUPPLY CHARACTERIST	ICS		-			
Power Supply Range		Full	2		12	V
Positive Supply Current, I+	V+ = 5.5V, $V_{IN}$ = 0V or V+, all channels on or off	Full	-1	0.0001	1	μA

NOTES:

5.  $V_{IN}$  = input voltage to perform proper function.

6. The algebraic convention, whereby the most negative value is a minimum and the most positive a maximum, is used in this data sheet.

7. Leakage parameter is 100% tested at high temp, and guaranteed by correlation at 25°C.

8.  $\Delta R_{ON} = R_{ON} (MAX) - R_{ON} (MIN)$ .

9. Flatness is defined as the difference between the maximum and minimum value of on-resistance over the specified analog signal range.

#### Electrical Specifications +3V Supply

Test Conditions: V+ = +2.7V to +3.6V, GND = 0V, V\_{AH} = 2.4V, V\_{AL}= 0.8V (Note 4), Unless Otherwise Specified

PARAMETER	TEST CONDITIONS	TEMP ( <sup>o</sup> C)	(NOTE 5) MIN	ТҮР	(NOTE 5) MAX	UNITS
ANALOG SWITCH CHARACTERIS	STICS	1	1			<u></u>
Analog Signal Range, V <sub>ANALOG</sub>		Full	0	-	V+	V
ON Resistance, R <sub>ON</sub>	$V$ + = 3.0V, $I_{COM}$ = 1.0mA, $V_{NO}$ or $V_{NC}$ = 1.5V,	25	-	190	220	Ω
	See Figure 5	Full	-	-	250	Ω
R <sub>ON</sub> Matching Between Channels,	V+ = 3.0V, $I_{COM}$ = 1.0mA, $V_{NO}$ or $V_{NC}$ = 1.5V, Note 7	25	-	1	3	Ω
ΔR <sub>ON</sub>		Full	-	-	5	Ω
R <sub>ON</sub> Flatness, R <sub>FLAT(ON)</sub>	V+ = 3.0V, $I_{COM}$ = 1.0mA, $V_{NO}$ or $V_{NC}$ = 0.5V, 1.5V,	25	-	48	90	Ω
	Note 8	Full	-	-	90	Ω
NO or NC OFF Leakage Current,	$V$ + = 3.6V, $V_{COM}$ = 1V, 3V, $V_{NO}$ or $V_{NC}$ = 3V, 1V,	25	-1	-	1	nA
INO(OFF) or INC(OFF)	Note 6	Full	-2.5	-	2.5	nA
COM OFF Leakage Current,	$V$ + = 3.6V, $V_{COM}$ = 3V, 1V, $V_{NO}$ or $V_{NC}$ = 1V, 3V,	25	-1	-	1	nA
ICOM(OFF)	Note 6	Full	-2.5	-	2.5	nA
COM ON Leakage Current,	$V_{+} = 3.6V, V_{COM} = 1V, 3V, \text{ or } V_{NO} \text{ or } V_{NC} = 1V, 3V,$	25	-1	-	1	nA
ICOM(ON)	or floating, Note 6	Full	-5	-	5	nA
DIGITAL INPUT CHARACTERIST	cs					
Input Voltage High, V <sub>INH</sub>		Full	2.0	1.0	-	V
Input Voltage Low, V <sub>INL</sub>		Full	-	0.8	0.5	V
Input Current, I <sub>INH</sub> , I <sub>INL</sub>	V+ = 3.6V, V <sub>IN</sub> = 0V or V+	Full	-0.5	-	0.5	μA
DYNAMIC CHARACTERISTICS			<u> </u>			
Inhibit Turn-ON Time, t <sub>ON</sub>	$V_{+} = 2.7V, V_{NO} \text{ or } V_{NC} = 1.5V, R_{L} = 300\Omega, C_{L} = 35pF,$	25	-	144	155	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	175	ns
Inhibit Turn-OFF Time, t <sub>OFF</sub>	$V_{+} = 2.7V, V_{NO} \text{ or } V_{NC} = 1.5V, R_{L} = 300\Omega, C_{L} = 35pF,$	25	-	53	60	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	65	ns
Address Transition Time, t <sub>TRANS</sub>	V+ = 2.7V, V <sub>NO</sub> or V <sub>NC</sub> = 1.5V, R <sub>L</sub> =300 $\Omega$ , C <sub>L</sub> = 35pF,	25	-	145	160	ns
	V <sub>IN</sub> = 0 to 3, See Figure 1	Full	-	-	190	ns
Break-Before-Make Time Delay, $t_D$	V+ = 3.6V, R <sub>L</sub> = 300 $\Omega$ , C <sub>L</sub> = 35pF, V <sub>NO</sub> or V <sub>NC</sub> = 1.5V, V <sub>IN</sub> = 0 to 3, See Figure 3	Full	15	35	-	ns

### Electrical Specifications +3V Supply

Test Conditions: V+ = +2.7V to +3.6V, GND = 0V, V<sub>AH</sub> = 2.4V, V<sub>AL</sub>= 0.8V (Note 4), Unless Otherwise Specified **(Continued)** 

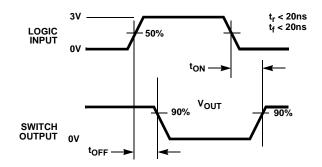
PARAMETER	TEST CONDITIONS	TEMP ( <sup>o</sup> C)	(NOTE 5) MIN	ТҮР	(NOTE 5) MAX	UNITS
	TEST CONDITIONS	(0)			MIAA	UNITS
Charge Injection, Q	$C_L = 1.0nF$ , $V_G = 0V$ , $R_G = 0\Omega$ , See Figure 2	25	-	0.5	1	рС
OFF Isolation	$R_L = 50\Omega$ , $C_L = 5pF$ , f = 1MHz, See Figure 4	25	-	75	-	dB
NO or NC OFF Capacitance, COFF	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	4	-	pF
COM OFF Capacitance, C <sub>COM(OFF)</sub>	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	11	-	pF
COM ON Capacitance, C <sub>COM(ON)</sub>	$f = 1MHz$ , $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	20	-	pF
POWER SUPPLY CHARACTERIST	ICS					
Positive Supply Current, I+	V+ = 3.6V, $V_{IN}$ = 0V or V+, all channels on or off	Full	-1	0.0001	1	μΑ

Electrical Specifications + 12V Supply

Test Conditions: V+ = +10.8V to +13.2V, GND = 0V, V\_{INH} = 4V, V\_{INL} = 0.8V (Note 5), Unless Otherwise Specified

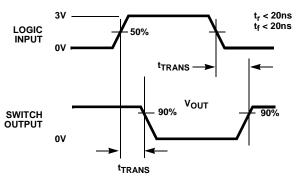
PARAMETER	TEST CONDITIONS	TEMP ( <sup>o</sup> C)	(NOTE 6) MIN	ТҮР	(NOTE6) MAX	UNITS
ANALOG SWITCH CHARACTERIS	STICS					
Analog Signal Range, VANALOG		Full	0	-	V+	V
ON Resistance, R <sub>ON</sub>	V+ = 12.0V, I <sub>COM</sub> = 1.0mA, V <sub>NO</sub> or V <sub>NC</sub> = 9V,	25	-	45	50	Ω
	See Figure 5	Full	-	-	70	Ω
RON Matching Between Channels,	$V_{+} = 12.0V, I_{COM} = 1.0mA, V_{NO} \text{ or } V_{NC} = 9V, \text{ Note } 7$	25	-	0.5	3	Ω
ΔR <sub>ON</sub>		Full	-	-	5	Ω
R <sub>ON</sub> Flatness, R <sub>FLAT(ON)</sub>	V+ = 13.2V, I <sub>COM</sub> = 1.0mA, V <sub>NO</sub> or V <sub>NC</sub> = 3V, 6V, 9V,	25	-	5	6	Ω
	Note 8	Full	-	-	10	Ω
NO or NC OFF Leakage Current,	V+ = 13.0V, $V_{COM}$ = 1V, 12V, $V_{NO}$ or $V_{NC}$ = 12V, 1V,	25	-1	-	1	nA
INO(OFF) or INC(OFF)	Note 7	Full	-2.5	-	2.5	nA
COM OFF Leakage Current,	$V$ + = 13.0V, $V_{COM}$ = 12V, 1V, $V_{NO}$ or $V_{NC}$ = 1V, 12V,	25	-1	-	1	nA
ICOM(OFF)	Note 7	Full	-2.5	-	2.5	nA
COM ON Leakage Current,	$V_{+} = 13.0V, V_{COM} = 1V, 12V, \text{ or } V_{NO} \text{ or } V_{NC} = 1V,$	25	-1	-	1	nA
ICOM(ON)	12V, or floating, Note 7	Full	-5	-	5	nA
DIGITAL INPUT CHARACTERIST	cs	I	1 1		1	1
Input Voltage High, V <sub>INH</sub>		Full	2.9	2.5	-	V
Input Voltage Low, VINL		Full	-	2.3	0.8	V
Input Current, I <sub>INH</sub> , I <sub>INL</sub>	V+ = 13V, V <sub>IN</sub> = 0V or V+	Full	-0.5	-	0.5	μA
DYNAMIC CHARACTERISTICS			4 4			
Inhibit Turn-ON Time, t <sub>ON</sub>	$V$ + = 10.8V, $V_{NO}$ or $V_{NC}$ = 10V, $R_L$ =300 $\Omega$ , $C_L$ = 35pF,	25	-	25	30	ns
	$V_{IN} = 0$ to 4, See Figure 1	Full	-		35	ns
Inhibit Turn-OFF Time, t <sub>OFF</sub>	V+ = 10.8V, V <sub>NO</sub> or V <sub>NC</sub> = 10V, R <sub>L</sub> = $300\Omega$ , C <sub>L</sub> = $35pF$ ,	25	-	24	28	ns
	$V_{IN} = 0$ to 4, See Figure 1	Full	-		30	ns
Address Transition Time, tTRANS	V+ = 10.8V, V <sub>NO</sub> or V <sub>NC</sub> = 10V, R <sub>L</sub> = $300\Omega$ , C <sub>L</sub> = $35pF$ ,	25	-	35	50	ns
	$V_{IN} = 0$ to 4, See Figure 1	Full	-		55	ns
Break-Before-Make Time Delay, tD	V+ = 13.2V, R <sub>L</sub> = 300 $\Omega$ , C <sub>L</sub> = 35pF, V <sub>NO</sub> or V <sub>NC</sub> = 10V, V <sub>IN</sub> = 0 to 4, See Figure 3	Full	3	9		ns
Charge Injection, Q	$C_L$ = 1.0nF, $V_G$ = 0V, $R_G$ = 0 $\Omega$ , See Figure 2	25	-	1.2	3	рС
OFF Isolation	$R_L = 50\Omega$ , $C_L = 5pF$ , f = 1MHz, See Figure 4	25	-	75	-	dB
NO or NC OFF Capacitance, COFF	$f = 1MHz$ , $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	4	-	pF
COM OFF Capacitance, <sup>C</sup> COM(OFF)	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	11	-	pF
COM ON Capacitance, C <sub>COM(ON)</sub>	f = 1MHz, $V_{NO}$ or $V_{NC} = V_{COM} = 0V$ , See Figure 6	25	-	20	-	pF
POWER SUPPLY CHARACTERIS		L	<u> </u>			1
Positive Supply Current, I+	$V$ + = 13.0V, $V_{IN}$ = 0V or V+, all channels on or off	Full	-1	0.0001	1	μA

## **Test Circuits and Waveforms**



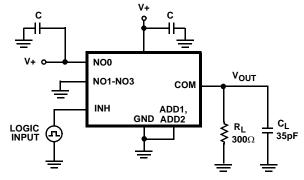
Logic input waveform is inverted for switches that have the opposite logic sense.





Logic input waveform is inverted for switches that have the opposite logic sense.

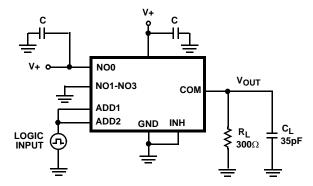
#### FIGURE 1C. ADDRESS MEASUREMENT POINTS



Repeat test for other switches. CL includes fixture and stray capacitance.

$$V_{OUT} = V_{(NO \text{ or } NC)} \frac{R_L}{R_L + R_{(ON)}}$$





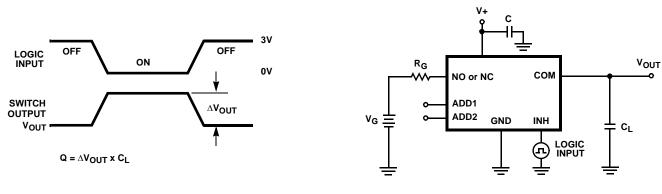
Repeat test for other switches. CL includes fixture and stray capacitance.

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$$V_{OUT} = V_{(NO \text{ or } NC)} \frac{R_L}{R_L + R_{(ON)}}$$

#### FIGURE 1D. ADDRESS TEST CIRCUIT



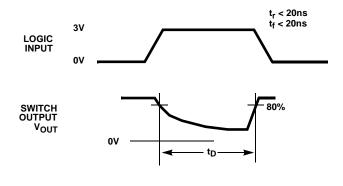


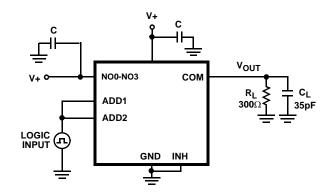
**FIGURE 2A. MEASUREMENT POINTS** 



**FIGURE 2B. TEST CIRCUIT** 







Repeat test for other switches.  $\mathbf{C}_{L}$  includes fixture and stray capacitance.

FIGURE 3A. MEASUREMENT POINTS

FIGURE 3B. TEST CIRCUIT



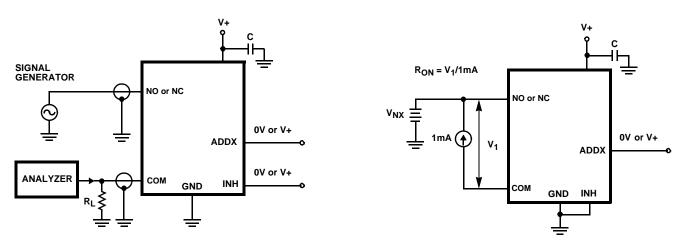




FIGURE 5. RON TEST CIRCUIT

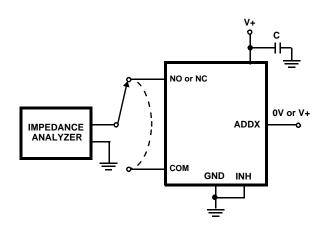


FIGURE 6. CAPACITANCE TEST CIRCUIT

## **Detailed Description**

The ISL43640 operates from a single 2V to 12V supply with low on-resistance (115 $\Omega$ ) and high speed operation (t<sub>ON</sub> = 160ns, t<sub>OFF</sub> = 30ns) with a +5V supply. The ISL43640 is especially well suited to portable battery powered equipment thanks to the low operating supply voltage (2.0V), low power consumption (3 $\mu$ W), low leakage currents (5nA max), and the tiny MSOP and QFN packaging. High frequency applications also benefit from the wide bandwidth, and the very high off isolation (75dB).

### Supply Sequencing And Overvoltage Protection

With any CMOS device, proper power supply sequencing is required to protect the device from excessive input currents which might permanently damage the IC. All I/O pins contain ESD protection diodes from the pin to V+ and GND (see Figure 7). To prevent forward biasing these diodes, V+ must be applied before any input signals, and input signal voltages must remain between V+ and GND. If these conditions cannot be guaranteed, then one of the following two protection methods should be employed.

Logic inputs can easily be protected by adding a  $1k\Omega$  resistor in series with the input (see Figure 7). The resistor limits the input current below the threshold that produces permanent damage, and the sub-microamp input current produces an insignificant voltage drop during normal operation.

This method is not applicable for the signal path inputs. Adding a series resistor to the switch input defeats the purpose of using a low  $R_{ON}$  switch, so two small signal diodes can be added in series with the supply pins to provide overvoltage protection for all pins (see Figure 7). These additional diodes limit the analog signal from 1V below V+ to 1V above GND. The low leakage current performance is unaffected by this approach, but the switch resistance may increase, especially at low supply voltages.

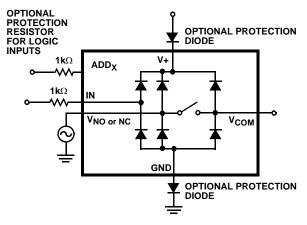


FIGURE 7. OVERVOLTAGE PROTECTION

### **Power-Supply Considerations**

The ISL43640 construction is typical of most CMOS analog switches, except that they have only two supply pins: V+ and GND. V+ and GND drive the internal CMOS switches and set their analog voltage limits. Unlike switches with a 13V maximum supply voltage, the ISL43640's 15V maximum supply voltage provides plenty of room for the 10% tolerance of 12V supplies, as well as room for overshoot and noise spikes.

The minimum recommended supply voltage is 2.0V. It is important to note that the input signal range, switching times, and on-resistance degrade at lower supply voltages. Refer to the electrical specification tables and *Typical Performance* curves for details.

V+ and GND also power the internal logic and level shifters. The level shifters convert the input logic levels to switched V+ and GND signals to drive the analog switch gate terminals.

The device cannot be operated with bipolar supplies, because the input switching point becomes negative in this configuration.

### Logic-Level Thresholds

The ISL43640 is TTL compatible (0.8V and 2.4V) over a supply range of 3V to 11V (see Figure 10). At 12V the V<sub>IH</sub> level is about 2.5V. This is still below the TTL guaranteed high output minimum level of 2.8V, but noise margin is reduced. For best results with a 12V supply, use a logic family the provides a V<sub>OH</sub> greater than 3V.

The digital input stages draw supply current whenever the digital input voltage is not at one of the supply rails (see Figure 11). Driving the digital input signals from GND to V+ with a fast transition time minimizes power dissipation. The ISL43640 has been designed to minimize the supply current whenever the digital input voltage is not driven to the supply rails (0V to V+). For example driving the device with 3V logic (0V to 3V) while operating with a 5V supply the device draws only 10 $\mu$ A of current (see Figure 11 for V<sub>IN</sub> = 3V). Similiar devices of competitors can draw 8 times this amount of current.

### High-Frequency Performance

In 50 $\Omega$  systems, signal response is reasonably flat even past 100MHz (see Figure 16). Figure 16 also illustrates that the frequency response is very consistent over a wide V+ range, and for varying analog signal levels.

An OFF switch acts like a capacitor and passes higher frequencies with less attenuation, resulting in signal feed through from a switch's input to its output. Off Isolation is the resistance to this feed through. Figure 17 details the high Off Isolation rejection provided by this family. At 10MHz, Off Isolation is about 55dB in 50 $\Omega$  systems, decreasing approximately 20dB per decade as frequency increases. Higher load impedances decrease Off Isolation due to the voltage divider action of the switch OFF impedance and the load impedance.

### Leakage Considerations

Reverse ESD protection diodes are internally connected between each analog-signal pin and both V+ and GND. One of these diodes conducts if any analog signal exceeds V+ or GND.

Virtually all the analog leakage current comes from the ESD diodes to V+ or GND. Although the ESD diodes on a given signal pin are identical and therefore fairly well balanced, they are reverse biased differently. Each is biased by either

V+ or GND and the analog signal. This means their leakages will vary as the signal varies. The difference in the two diode leakages to the V+ and GND pins constitutes the analogsignal-path leakage current. All analog leakage current flows between each pin and one of the supply terminals, not to the other switch terminal. This is why both sides of a given switch can show leakage currents of the same or opposite polarity. There is no connection between the analog signal paths and V+ or GND.

## **Die Characteristics**

Typical Performance Curves T<sub>A</sub> = 25°C, Unless Otherwise Specified

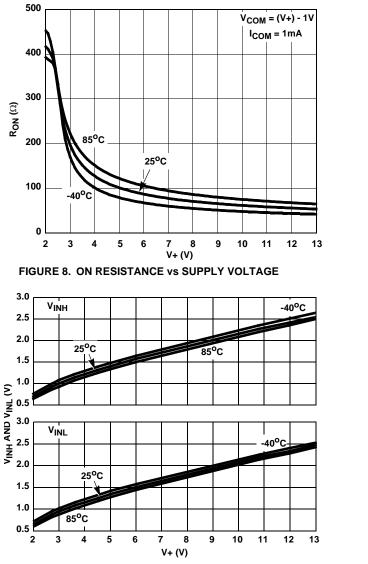


FIGURE 10. DIGITAL SWITCHING POINT vs SUPPLY VOLTAGE

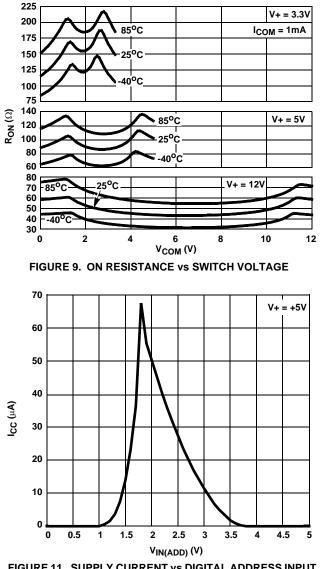


FIGURE 11. SUPPLY CURRENT vs DIGITAL ADDRESS INPUT VOLTAGE

# Typical Performance Curves $T_A = 25^{\circ}C$ , Unless Otherwise Specified (Continued)

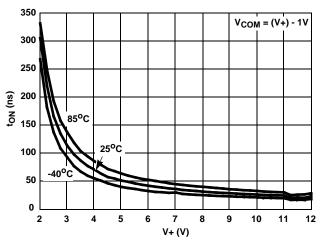


FIGURE 12. TURN - ON TIME vs SUPPLY VOLTAGE

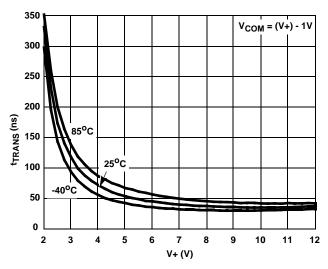
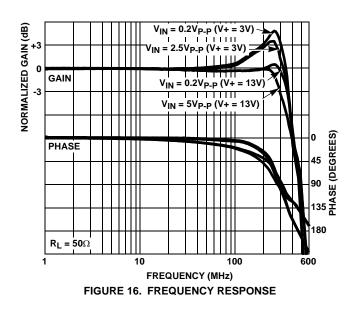


FIGURE 14. ADDRESS TRANS TIME vs SUPPLY VOLTAGE



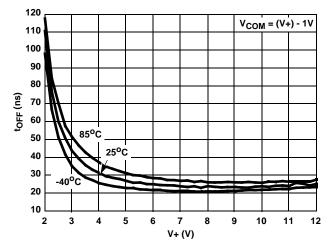


FIGURE 13. TURN - OFF TIME vs SUPPLY VOLTAGE

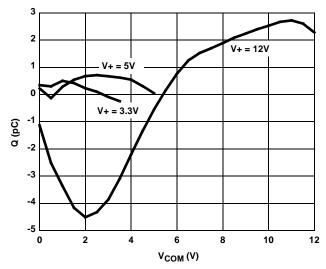
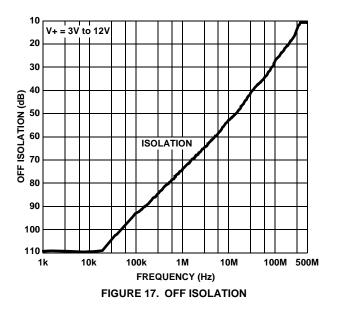


FIGURE 15. CHARGE INJECTION vs SWITCH VOLTAGE



## **Die Characteristics**

### SUBSTRATE POTENTIAL (POWERED UP):

GND

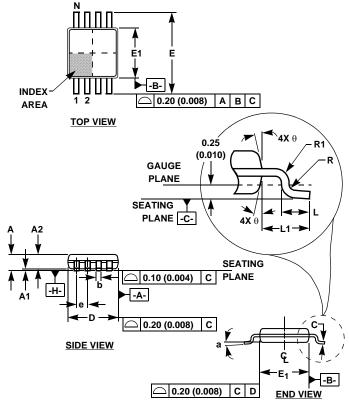
### TRANSISTOR COUNT:

193

## PROCESS:

Si Gate CMOS





#### NOTES:

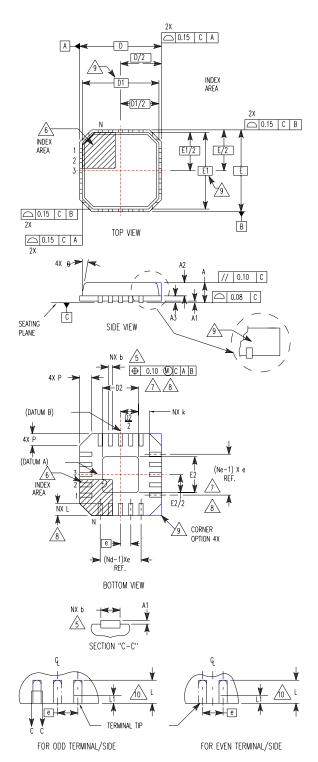
- 1. These package dimensions are within allowable dimensions of JEDEC MO-187BA.
- 2. Dimensioning and tolerancing per ANSI Y14.5M-1994.
- 3. Dimension "D" does not include mold flash, protrusions or gate burrs and are measured at Datum Plane. Mold flash, protrusion and gate burrs shall not exceed 0.15mm (0.006 inch) per side.
- Dimension "E1" does not include interlead flash or protrusions and are measured at Datum Plane. -H- Interlead flash and protrusions shall not exceed 0.15mm (0.006 inch) per side.
- 5. Formed leads shall be planar with respect to one another within 0.10mm (.004) at seating Plane.
- 6. "L" is the length of terminal for soldering to a substrate.
- 7. "N" is the number of terminal positions.
- 8. Terminal numbers are shown for reference only.
- 9. Dimension "b" does not include dambar protrusion. Allowable dambar protrusion shall be 0.08mm (0.003 inch) total in excess of "b" dimension at maximum material condition. Minimum space between protrusion and adjacent lead is 0.07mm (0.0027 inch).
- 10. Datums -A and -B to be determined at Datum plane
- 11. Controlling dimension: MILLIMETER. Converted inch dimensions are for reference only

### M10.118 (JEDEC MO-187BA)

10 LEAD MINI SMALL OUTLINE PLASTIC PACKAGE

	INC	HES	MILLIN	MILLIMETERS		
SYMBOL	MIN	MAX	MIN	MAX	NOTES	
А	0.037	0.043	0.94	1.10	-	
A1	0.002	0.006	0.05	0.15	-	
A2	0.030	0.037	0.75	0.95	-	
b	0.007	0.011	0.18	0.27	9	
С	0.004	0.008	0.09	0.20	-	
D	0.116	0.120	2.95	3.05	3	
E1	0.116	0.120	2.95	3.05	4	
е	0.020	BSC	0.50	BSC	-	
E	0.187	0.199	4.75	5.05	-	
L	0.016	0.028	0.40	0.70	6	
L1	0.037	0.037 REF		REF	-	
Ν	1	10		10	7	
R	0.003	-	0.07	-	-	
R1	0.003	-	0.07	-	-	
θ	5 <sup>0</sup>	15 <sup>0</sup>	5 <sup>0</sup>	15 <sup>0</sup>	-	
α	0 <sup>0</sup>	6 <sup>0</sup>	0 <sup>0</sup>	6 <sup>0</sup>	-	





### L16.3x3

16 LEAD QUAD FLAT NO-LEAD PLASTIC PACKAGE (COMPLIANT TO JEDEC MO-220VEED-2 ISSUE C)

	IO JEDEC		1330E C)	
	MILLIMETERS			
SYMBOL	MIN	NOMINAL	MAX	NOTES
А	0.80	0.90	1.00	-
A1	-	-	0.05	-
A2	-	-	1.00	9
A3	0.20 REF			9
b	0.18	0.23	0.30	5, 8
D	3.00 BSC			-
D1	2.75 BSC			9
D2	1.35	1.50	1.65	7, 8
E	3.00 BSC			-
E1		2.75 BSC		9
E2	1.35	1.50	1.65	7, 8
е		0.50 BSC		-
k	0.25	-	-	-
L	0.30	0.40	0.50	8
L1	-	-	0.15	10
Ν		16		2
Nd		4		3
Ne		4		3
Р	-	-	0.60	9
θ	-	-	12	9
Rev. 0 10/02				

NOTES:

- 1. Dimensioning and tolerancing conform to ASME Y14.5-1994.
- 2. N is the number of terminals.
- 3. Nd and Ne refer to the number of terminals on each D and E.
- 4. All dimensions are in millimeters. Angles are in degrees.
- 5. Dimension b applies to the metallized terminal and is measured between 0.15mm and 0.30mm from the terminal tip.
- 6. The configuration of the pin #1 identifier is optional, but must be located within the zone indicated. The pin #1 identifier may be either a mold or mark feature.
- 7. Dimensions D2 and E2 are for the exposed pads which provide improved electrical and thermal performance.
- 8. Nominal dimensions are provided to assist with PCB Land Pattern Design efforts, see Intersil Technical Brief TB389.
- 9. Features and dimensions A2, A3, D1, E1, P & 0 are present when Anvil singulation method is used and not present for saw singulation.
- Depending on the method of lead termination at the edge of the package, a maximum 0.15mm pull back (L1) maybe present. L minus L1 to be equal to or greater than 0.3mm.

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